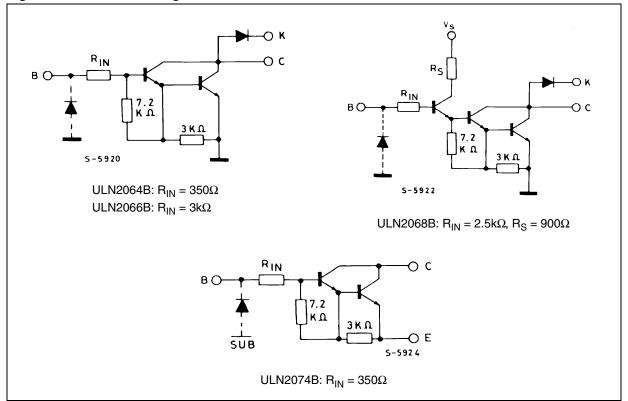
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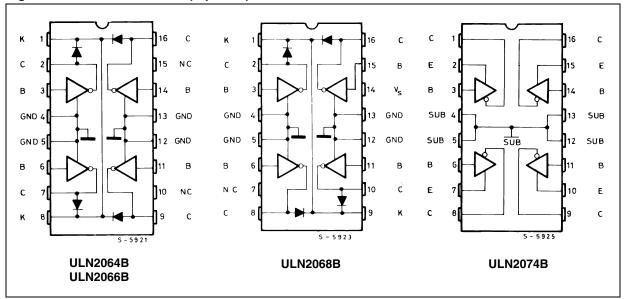
1 Diagram

Figure 1. Schematic diagrams



2 Pin configuration

Figure 2. Pin connections (top view)



3 Maximum ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit	
V _{CEX}	Output voltage	50	V	
V _{CE(SUS)}	Output sustaining voltage	35	V	
Io	Output current	1.75	Α	
V	Input voltage ULN2066B - 2074B	30	V	
V _I	Input voltage ULN2064B - 2068B	15		
I _I	Input current	25	mA	
V _S	Supply voltage for ULN2068B	10	V	
Р.	Power dissipation at T _{PINS} = 90 °C	4.3	w	
P _{TOT}	Power dissipation at T _{AMB} = 70 °C	1] **	
T _{AMB}	Operating ambient temperature range	- 20 to 85	°C	
T _{STG}	Storage temperature	- 55 to 150	°C	

4 Electrical characteristics

Table 3. Electrical characteristics ($T_A = 25$ °C unless otherwise specified).

Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit			
I _{CEX}	Output leakage current	V _{CE} = 50V, T _A = 25°C			100				
	(Figure 5)	V _{CE} = 50V, T _A = 70°C		500	μΑ				
V _{CE(SUS)}	Collector-emitter sustaining voltage (Figure 4)	I _C = 100mA, V _I = 0.4V	35			V			
		$I_C = 500$ mA, $I_B = 325$ μ A			1.1	V			
V	Collector-emitter saturation voltage (Figure 5)	$I_C = 750 \text{mA}, I_B = 935 \mu \text{A}$			1.2				
$V_{CE(SAT)}$		I _C = 1A, I _B = 1.25mA			1.3				
		$I_C = 1.25A$, $I_B = 2mA$			1.4				
I _{I(ON)}	Input current (<i>Figure 6</i>)	for ULN2064B and ULN2074B $V_{l} = 2.4V$ $V_{l} = 3.75V$	1.4 3.3		4.3 9.6	mA			
		for ULN2066B, V _I = 5V V _I = 12V	0.6 1.7		1.8 5.2				
		for ULN2068B, V _I = 2.75V V _I = 3.75V			0.55 1.0				
V _{I(ON)}	Input voltage (Figure 7)	V_{CE} = 2V, I_{C} = 1A ULN2064B, ULN2074B, ULN2066B V_{CE} = 2V, I_{C} = 1.5A ULN2064B, ULN2074B, ULN2066B ULN2068B			2 6.5 2.5 10 2.75	V			
I _S	Supply current (Figure 10)	for ULN2068B, V _I = 2.75V, I _C = 500mA			6	mA			
t _{PLH}	Turn-on delay time	0.5 V _I to 0.5V _O			1	μs			
t _{PHL}	Turn-off delay time	0.5 V _I to 0.5V _O			1.5	μs			
I _R	Clamp diode leakage current (Figure 8)	For ULN2064B - ULN2066B - ULN2068B, V _R = 50V T _A = 25°C T _A = 70°C			50 100	μΑ			
V _F	Clamp diode forward voltage (Figure 9)	For ULN2064B - ULN2066B - ULN2068B IF = 1A IF = 1.5A			1.75 2	V			

Note: Input voltage is with reference to the substrate (no connection to any other pins) for the

ULN2074B reference is ground for all other types.

Note: 1 Input current may be limited by maximum allowable input voltage.

5 **Test circuits**

OPEN

Figure 3. Output leakage current

Figure 4. Collector-emitter sustaining voltage OPEN VCE OPEN v_{CE} S-5725

Collector-emitter saturation voltage Figure 6. Figure 5. Input current (ON)

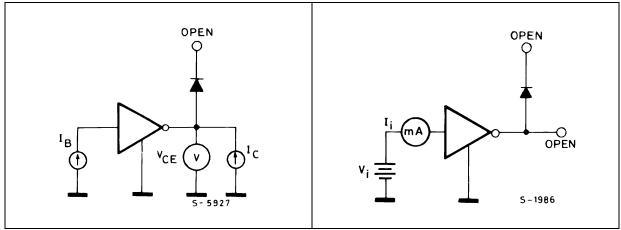


Figure 7. Input voltage Figure 8. Clamp diode leakage current OPEN OPEN V_{CE} 0 S - 5727 S - 1987

Figure 9. Clamp diode forward voltage

Figure 10. Supply current

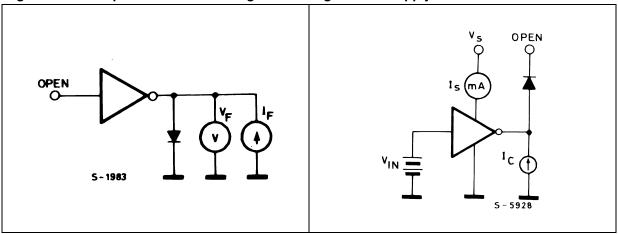


Figure 11. Input current as a function of input Figure 12. Input current as a function of input voltage

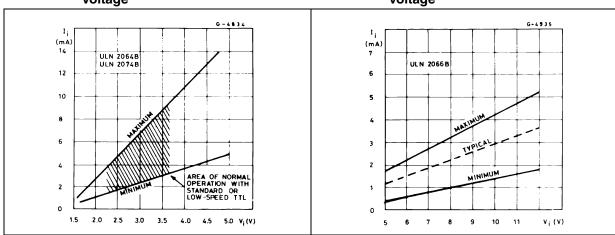
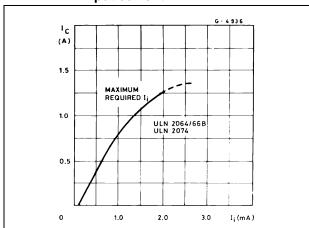


Figure 13. Collector current as a function of input current



6 Mounting instructions

The R_{thJA} can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board (*Figure 14*) or to an external heatsink (*Figure 15*).

The diagram of *Figure 16* shows the maximum dissipated power P_{TOT} and the R_{thJA} as a function of the side " α " of two equal square copper areas having a thickness of 35 μ (1.4 mils).

During soldering the pins temperature must not exceed 260 °C and the soldering time must not be longer than 12 seconds.

The external heatsink or printed circuit copper area must be connected to electrical ground.

Figure 14. Example of P.C. board area which is Figure 15. External heatsink mounting used as heatsink example

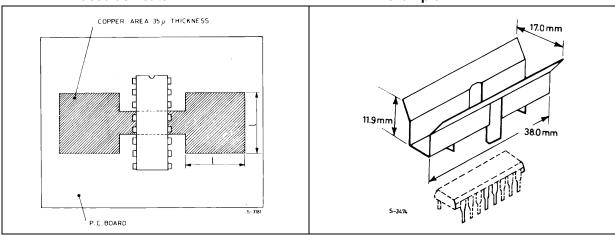
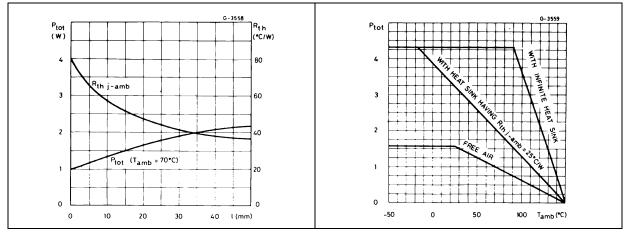


Figure 16. Maximum dissipated power and junction to ambient thermal resistance vs. side "\alpha"

Figure 17. Maximum allowable power dissipation vs. ambient temperature



7 Typical applications

Figure 18. Common-anode LED drivers

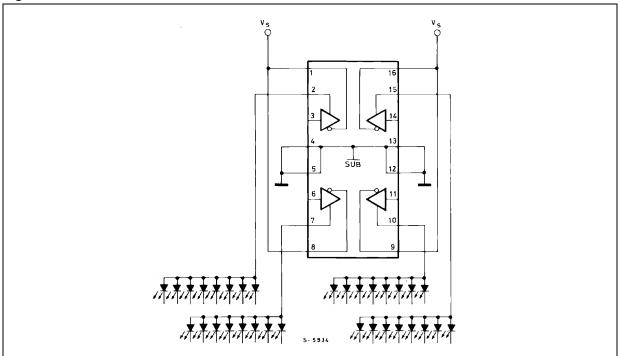
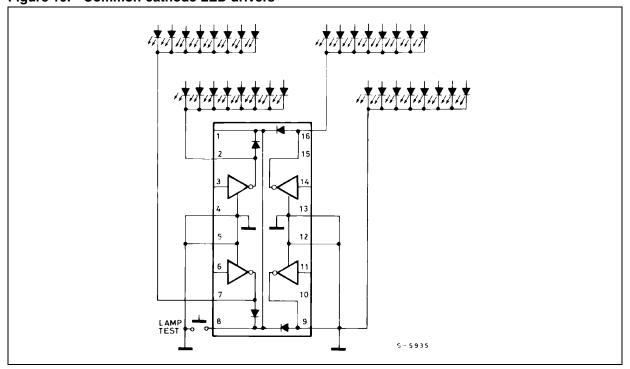


Figure 19. Common-cathode LED drivers

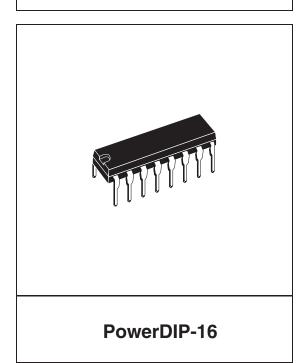


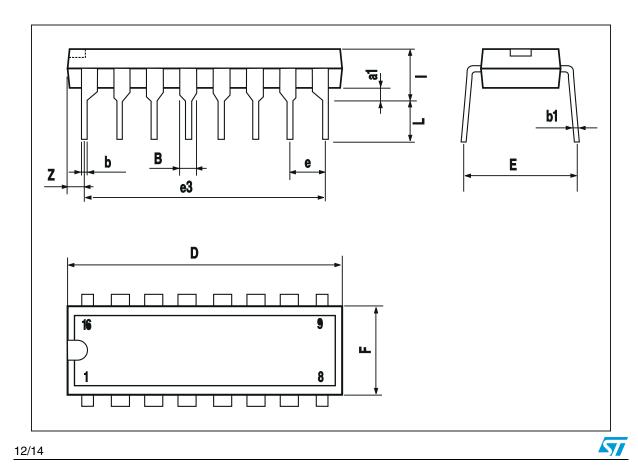
8 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Dim.	mm			inch.		
	Min.	Тур.	Max.	Min.	Тур.	Max.
a1	0.51			0.020		
В	0.85		1.40	0.033		0.055
b		0.50			0.020	
b1	0.38		0.50	0.015		0.020
D			20.0			0.787
Е		8.80			0.346	
е		2.54			0.100	
e3		17.78			0.700	
F			7.10			0.280
I			5.10			0.201
L		3.30			0.130	
Z			1.27			0.050

OUTLINE AND MECHANICAL DATA





9 Revision history

Table 4. Document revision history

Date	Revision	Changes	
12-Sep-2003	1	First release	
22-Jan-2009	2	Modified Table 1 on page 1.	

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